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Standard for signal and test definition

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CONTENTS

FOREWORD.....	10
IEEE introduction.....	13
1. Overview.....	14
1.1 Scope.....	14
1.2 Purpose.....	15
2. Definitions, abbreviations, and acronyms.....	15
2.1 Definitions	15
2.2 Abbreviations and acronyms	17
3. Structure of this standard	18
3.1 Layers.....	18
4. Signal modeling language (SML) layer.....	20
5. Basic signal component (BSC) layer	20
5.1 BSC layer base classes.....	20
5.2 BSCs	21
5.3 SignalFunction template	22
6. Test signal framework (TSF) layer	22
6.1 TSF classes	22
6.2 TSF signals	23
7. Test procedure language (TPL) layer	25
7.1 Goals of the TPL.....	25
7.2 Elements of the TPL	25
7.3 Use of the TPL.....	25
Annex A (normative) Signal modeling language (SML)	26
A.1 Use of the SML.....	26
A.2 Introduction.....	26
A.3 Physical types	27
A.4 Signal definitions	30
A.5 Pure signals	31
A.5.1 Nonperiodic signals.....	31
A.5.2 Periodic signals	32
A.6 Pure signal-combining mechanisms	33
A.6.1 Piecewise continuous signals (PCSs).....	33
A.6.2 Sum.....	36
A.6.3 Product	36
A.7 Pure function transformations.....	36
A.7.1 Fourier transform.....	37
A.8 Measuring, limiting, and sampling signals	37
A.8.1 Confining parameters to a limit.....	38
A.8.2 Sampling signals	38
A.9 Digital signals	38

A.9.1	Defining Digital.....	39
A.9.2	Defining DigitalSignal	39
A.9.3	Conversion routines.....	40
A.9.4	Patterns	41
A.10	Basic component SML.....	42
A.10.1	Source ::SignalFunction	42
A.10.2	Conditioner ::SignalFunction	44
A.10.3	EventFunction ::SignalFunction.....	47
A.10.4	Sensor ::SignalFunction	50
A.10.5	Digital ::SignalFunction	50
A.10.6	Connection ::SignalFunction.....	51
Annex B (normative) Basic signal component (BSC) layer.....		53
B.1	BSC layer base classes.....	53
B.2	BSC subclasses	53
B.3	Description of a BSC	58
B.3.1	Diagrammatic representation of a BSC.....	58
B.3.2	BSC interfaces.....	59
B.3.3	Types of BSCs.....	60
B.3.4	BSC attribute default values.....	61
B.3.5	BSC subclass descriptions.....	61
B.4	Physical class	63
B.4.1	Permissible physical types and their units.....	65
B.4.2	Unit prefixes	69
B.5	PulseDefns class	70
B.5.1	PulseDefn class	71
B.6	SignalFunction class	71
B.6.1	Source ::SignalFunction	72
B.6.2	Conditioner ::SignalFunction	80
B.6.3	EventFunction ::SignalFunction.....	94
B.6.4	Sensor ::SignalFunction	100
B.6.5	Digital ::SignalFunction	106
B.6.6	Connection ::SignalFunction.....	108
Annex C (normative) Dynamic signal descriptions.....		112
C.1	Introduction.....	112
C.2	Basic classes	113
C.2.1	ResourceManager.....	113
C.2.2	Signal.....	114
C.2.3	BSCs.....	116
C.3	Dynamic signal goals and use cases	118
Annex D (normative) IDL basic components.....		119
D.1	Introduction.....	119
D.2	IDL BSC library.....	119
Annex E (informative) Test signal framework (TSF) for ATLAS		161
E.1	Introduction.....	161
E.2	AC_SIGNAL<type: Current Power Voltage>	161
E.2.1	Definition	161
E.2.2	Interface properties.....	162

E.2.3	Notes.....	162
E.2.4	Model description.....	162
E.2.5	Rules.....	162
E.2.6	Example.....	163
E.3	AM_SIGNAL	163
E.3.1	Definition	163
E.3.2	Interface properties.....	164
E.3.3	Notes.....	164
E.3.4	Model description.....	164
E.3.5	Rules.....	165
E.3.6	Example.....	165
E.4	DC_SIGNAL<type: Voltage Current Power>	165
E.4.1	Definition	165
E.4.2	Interface properties.....	166
E.4.3	Notes.....	166
E.4.4	Model description.....	166
E.4.5	Rules.....	167
E.4.6	Example.....	167
E.5	DIGITAL_PARALLEL	168
E.5.1	Definition	168
E.5.2	Interface properties.....	168
E.5.3	Notes.....	168
E.5.4	Model description.....	169
E.5.5	Rules.....	169
E.5.6	Example.....	169
E.6	DIGITAL_SERIAL	170
E.6.1	Definition	170
E.6.2	Interface properties.....	171
E.6.3	Notes.....	171
E.6.4	Model description.....	171
E.6.5	Rules.....	171
E.6.6	Example.....	172
E.7	DME_INTERROGATION	172
E.7.1	Definition	172
E.7.2	Interface properties.....	173
E.7.3	Notes.....	173
E.7.4	Model description.....	174
E.7.5	Rules.....	164
E.7.6	Example.....	174
E.8	DME_RESPONSE	175
E.8.1	Definition	175
E.8.2	Interface properties.....	176
E.8.3	Notes.....	177
E.8.4	Model description.....	177
E.8.5	Rules.....	179
E.8.6	Example.....	179
E.9	FM_SIGNAL<type: Voltage Power Current>	180
E.9.1	Definition	180
E.9.2	Interface properties.....	180
E.9.3	Notes.....	180
E.9.4	Model description.....	180
E.9.5	Rules.....	181
E.9.6	Example.....	181
E.10	ILS_GLIDE_SLOPE<type: Voltage Power>	182

E.10.1	Definition	182
E.10.2	Interface properties.....	183
E.10.3	Notes.....	184
E.10.4	Model description.....	184
E.10.5	Rules.....	185
E.10.6	Example.....	185
E.11	ILS_LOCALIZER<type: Power Voltage>	186
E.11.1	Definition	186
E.11.2	Interface properties.....	186
E.11.3	Notes.....	187
E.11.4	Model description.....	187
E.11.5	Rules.....	188
E.11.6	Example.....	188
E.12	ILS_MARKER	189
E.12.1	Definition	189
E.12.2	Interface properties.....	190
E.12.3	Notes.....	190
E.12.4	Model description.....	190
E.12.5	Rules.....	191
E.12.6	Example.....	191
E.13	PM_SIGNAL	191
E.13.1	Definition	191
E.13.2	Interface properties.....	192
E.13.3	Notes.....	192
E.13.4	Model description.....	192
E.13.5	Rules.....	193
E.13.6	Example.....	193
E.14	PULSED_AC_SIGNAL<type: Current Power Voltage>	194
E.14.1	Definition	194
E.14.2	Interface properties.....	194
E.14.3	Notes.....	194
E.14.4	Model description.....	195
E.14.5	Rules.....	195
E.14.6	Example.....	195
E.15	PULSED_AC_TRAIN<type: Voltage Current Power>	196
E.15.1	Definition	196
E.15.2	Interface properties.....	196
E.15.3	Notes.....	197
E.15.4	Model description.....	197
E.15.5	Rules.....	197
E.15.6	Example.....	198
E.16	PULSED_DC_SIGNAL<type: Voltage Current Power>	198
E.16.1	Definition	198
E.16.2	Interface properties.....	199
E.16.3	Notes.....	199
E.16.4	Model description.....	199
E.16.5	Rules.....	200
E.16.6	Example.....	200
E.17	PULSED_DC_TRAIN<type: Voltage Current Power>	201
E.17.1	Definition	201
E.17.2	Interface properties.....	201
E.17.3	Notes.....	201
E.17.4	Model description.....	202
E.17.5	Rules.....	202

E.17.6	Example.....	202
E.18	RADAR_RX_SIGNAL	203
E.18.1	Definition	203
E.18.2	Interface properties.....	203
E.18.3	Notes.....	204
E.18.4	Model description.....	204
E.18.5	Rules.....	205
E.18.6	Example.....	205
E.19	RADAR_TX_SIGNAL<type: Current Voltage Power>	206
E.19.1	Definition	206
E.19.2	Interface properties.....	206
E.19.3	Notes.....	207
E.19.4	Model description.....	207
E.19.5	Rules.....	207
E.19.6	Example.....	207
E.20	RAMP_SIGNAL<type: Voltage Current Power>	208
E.20.1	Definition	208
E.20.2	Interface properties.....	209
E.20.3	Notes.....	209
E.20.4	Model description.....	209
E.20.5	Rules.....	209
E.20.6	Example.....	210
E.21	RANDOM_NOISE	210
E.21.1	Definition	210
E.21.2	Interface properties.....	210
E.21.3	Notes.....	211
E.21.4	Model description.....	211
E.21.5	Rules.....	211
E.21.6	Example.....	211
E.22	RESOLVER	212
E.22.1	Definition	212
E.22.2	Interface properties.....	213
E.22.3	Notes.....	213
E.22.4	Model description.....	213
E.22.5	Rules.....	214
E.22.6	Example.....	215
E.23	RS_232.....	215
E.23.1	Definition	215
E.23.2	Interface properties.....	215
E.23.3	Notes.....	216
E.23.4	Model description.....	216
E.23.5	Rules.....	216
E.24	SQUARE_WAVE<type: Current Voltage Power>	216
E.24.1	Definition	216
E.24.2	Interface properties.....	217
E.24.3	Notes.....	217
E.24.4	Model description.....	217
E.24.5	Rules.....	218
E.24.6	Example.....	218
E.25	SSR_INTERROGATION<type: Voltage Current Power>	219
E.25.1	Definition	219
E.25.2	Interface properties.....	219
E.25.3	Notes.....	220
E.25.4	Model description.....	221

E.25.5	Rules	221
E.25.6	Example	221
E.26	SSR_RESPONSE<type: Voltage Current Power>	222
E.26.1	Definition	222
E.26.2	Interface properties	222
E.26.3	Notes	223
E.26.4	Model description	224
E.26.5	Rules	225
E.26.6	Example	225
E.27	STEP_SIGNAL	226
E.27.1	Definition	226
E.27.2	Interface properties	226
E.27.3	Notes	227
E.27.4	Model description	227
E.27.5	Rules	227
E.27.6	Example	227
E.28	SUP_CAR_SIGNAL	228
E.28.1	Definition	228
E.28.2	Interface properties	228
E.28.3	Notes	229
E.28.4	Model description	229
E.28.5	Rules	230
E.28.6	Example	230
E.29	SYNCHRO	230
E.29.1	Definition	230
E.29.2	Interface properties	231
E.29.3	Notes	232
E.29.4	Model description	232
E.29.5	Rules	233
E.29.6	Example	233
E.30	TACAN	234
E.30.1	Definition	234
E.30.2	Interface properties	235
E.30.3	Notes	236
E.30.4	Model description	236
E.30.5	Rules	238
E.30.6	Example	238
E.31	TRIANGULAR_WAVE_SIGNAL<type: Voltage Current Power>	239
E.31.1	Definition	239
E.31.2	Interface properties	239
E.31.3	Notes	240
E.31.4	Model description	240
E.31.5	Rules	240
E.31.6	Example	240
E.32	VOR	241
E.32.1	Definition	241
E.32.2	Interface properties	242
E.32.3	Notes	242
E.32.4	Model description	243
E.32.5	Rules	244
E.32.6	Example	244
Annex F (informative) IDL for TSF for ATLAS		245

F.1	Introduction.....	245
F.2	IDL for TSF for ATLAS library.....	245
Annex G (normative) Carrier language requirements		265
G.1	Carrier language requirements.....	265
G.1.1	General requirements	265
G.1.2	Human interface and communication.....	265
G.2	IDL.....	265
G.3	Data types	265
G.3.1	Enumeration data type.....	266
G.3.2	Integer data type	266
G.3.3	Real data type	266
G.3.4	Character data type.....	267
G.3.5	Boolean data type.....	267
G.3.6	File data type	267
G.3.7	Array data type	267
G.3.8	Record data type.....	267
G.3.9	Variables and constants	267
G.4	Data-processing requirements.....	267
G.4.1	Data manipulation	267
G.4.2	Arithmetic operators.....	268
G.4.3	Relational operators.....	268
G.4.4	Logical operators.....	268
G.4.5	Other operators	269
G.4.6	Mathematical functions	269
G.4.7	File-handling functions	269
G.4.8	Type conversion functions	270
G.4.9	String related functions	270
G.4.10	Other functions	271
G.5	Control structures.....	271
G.5.1	If.....	271
G.5.2	Else	271
G.5.3	Case	271
G.5.4	For	271
G.5.5	While	271
Annex H (normative) Test procedure language (TPL).....		273
H.1	TPL layer	273
H.2	Elements of the TPL	273
H.3	Structure of test requirements	273
H.4	Carrier language.....	273
H.5	Signal statements	273
H.5.1	Definition of signal statements.....	273
H.5.2	Structure of signal statements	274
H.5.3	Syntax of signal statements	274
H.6	Mapping of test statements to carrier language	275
H.7	Test statement definitions	275
H.7.1	Setup statements.....	275
H.7.2	Reset statement.....	283
H.7.3	Connect statement	284
H.7.4	Disconnect statement.....	286
H.7.5	Enable statement	287

H.7.6	Disable statement	288
H.7.7	Read statement	289
H.7.8	Change statement	290
H.7.9	Compare statement	290
H.7.10	Wait_For statement	292
H.8	Elements used in test statement definitions	292
H.8.1	<TSFClass>	292
H.8.2	Attribute-Value groups.....	293
H.9	Attributes with multiple properties	300
H.9.1	Entering literal data	300
H.9.2	Using arrays of data.....	302
H.9.3	Acquiring sensor data.....	303
H.10	Transferring data in digital signals	304
H.10.1	Representation of digital data.....	304
H.10.2	Transmitting digital data using digital sources	305
H.10.3	Acquiring digital sensor data.....	307
H.10.4	Bidirectional digital signals.....	307
H.11	Creating test requirements	308
H.11.1	Creating test statements.....	308
H.11.2	Use of gate in signal statements	309
H.12	Delimiting TPL statements	310
H.12.1	Introducing a group of one or more TPL statements.....	310
H.12.2	Indicating end of group of TPL statements.....	310
Annex I (normative) Extensible markup language (XML) signal descriptions (XSDs)		312
I.1	Introduction.....	312
I.2	XML signal schema definition	312
Annex J (informative) XML for TSF for ATLAS		350
J.1	Introduction.....	350
J.2	TSF XML schema.....	350
J.2.1	Library information (<TSFLibrary> tag)	350
J.2.2	TSF information (<TSF> tag)	350
J.2.3	Interface information (<interface> tag).....	351
J.2.4	Model information (<model> tag).....	351
J.2.5	XML schema	352
J.3	XML for TSF for ATLAS	353
Annex K (informative) Support for ATLAS nouns and modifiers.....		398
K.1	STD support for ATLAS signals	398
K.2	STD support for ATLAS nouns.....	398
K.3	STD support for ATLAS noun modifiers	401
K.3.1	Example of noun modifier supported by combination of BSCs	411
K.3.2	Example of noun modifier supported by a technique.....	411
K.4	Support for ATLAS extensions	411
Annex L (informative) Bibliography		412
Annex M (informative) List of participants		413

INTERNATIONAL ELECTROTECHNICAL COMMISSION

STANDARD FOR SIGNAL AND TEST DEFINITION

FOREWORD

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The text of this standard is based on the following documents:

IEEE Std	FDIS	Report on voting
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Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

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- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
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IEEE Standard for Signal and Test Definition

Sponsor

**IEEE Standards Coordinating Committee 20 on
Test and Diagnosis for Electronic Systems**

Approved 2 February 2005

American National Standards Institute

Approved 23 September 2004

IEEE-SA Standards Board

Abstract: This standard provides the means to define and describe signals used in testing. It also provides a set of common basic signals, mathematically underpinned so that signals can be combined to form complex signals usable across all test platforms.

Keywords: ATE, ATLAS, automatic test equipment, signal definitions, test definitions, test requirements, test signals, unit under test, UUT

IEEE Introduction

This standard is the culmination of a radical review of the Abbreviated Test Language for All Systems (ATLAS) and the requirement to create truly portable test requirements. During the review process, it was determined that it would be impractical to revise the existing ATLAS standard to include the required improvements. The decision was made to formulate a new standard to resolve these issues.

The key feature of the signal and test definition (STD) in this standard is the ability to unambiguously define test signals. It includes a rigorous mathematical and definitive foundation for all of its signal components. Any signal defined using this standard will be the same whatever equipment is used to create it. The standard supports the implementation of new technologies by providing users with the ability to describe their own signals by combining existing signals. Thus, any desired signal may be described, and there is no limit on the extensibility of signals supported by this standard.

Signals defined using STD can be used in a programming environment of the user's choice provided that that environment fulfills the minimum requirements stated in this standard. This universality enables the user to take full advantage of modern program structures and development environments, including graphical programming environments.

This standard was developed by the Test Description Subcommittee, whose intention is to prepare a companion guide to explain how to implement signal definitions and test requirements in conformance with STD.

Notice to users

Errata

Errata, if any, for this and all other standards can be accessed at the following URL: <http://standards.ieee.org/reading/ieee/updates/errata/index.html>. Users are encouraged to check this URL for errata periodically.

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STANDARD FOR SIGNAL AND TEST DEFINITION

1. Overview

This standard, also known as the signal and test definition (STD) standard, is the culmination of a radical review of the Abbreviated Test Language for All Systems (ATLAS) test programming language and the requirement to create truly portable test requirements. STD will allow test information to pass more freely between the design, test, and maintenance phases of a project, enabling the same information to be used directly across project phases. This more efficient use of information will lead to reduced life-cycle costs.

STD provides the capability to describe and control signals, while permitting a choice of operating environment, including the choice of carrier language. STD permits signal operations to be embedded in any object-oriented environment and thus to be used by the architecture standards of various automatic test systems (ATSS).

Portability is extended beyond that of test specifications by virtue of a layered architecture.

STD defines a collection of objects and their interfaces. These objects describe signal components relevant to test requirements. The STD standard defines how to interconnect these objects using interfaces, through which the objects exchange information, so that a test model may be defined that describes actual test requirements.

Finally, the link to published ATLAS standards (such as IEEE Std 716TM-1995 [B9]¹) is preserved in that the user can describe signal operations using very similar test-signal-related keywords. These keywords now have formal definitions. Furthermore, the parameters of the signals themselves also have a rigorous formal behavioral description.

1.1 Scope

This standard provides the means to define and describe signals used in testing. It also provides a set of common basic signals, mathematically underpinned so that signals can be combined to form complex signals usable across all test platforms. The provision of language elements supports test signal descriptions for interoperability.

¹The numbers in brackets correspond to the numbers of the bibliography in Annex L.

This standard is divided into seven clauses:

- Clause 1 provides an introduction to this standard.
- Clause 2 provides definitions of terms and lists abbreviations.
- Clause 3 describes the structure of the STD standard.
- Clause 4 specifies the signal modeling language (SML).
- Clause 5 specifies the STD basic signal components (BSCs).
- Clause 6 defines the test signal frameworks (TSFs).
- Clause 7 describes the test procedure language (TPL) layer.

This standard also contains the following annexes:

- a) Annex A provides the Signals Modeling Language that is used to construct the BSCs and the TSFs.
- b) Annex B provides BSC descriptions.
- c) Annex C provides dynamic signal model description, states, and state transitions.
- d) Annex D provides the interface definition language (IDL) description for the BSCs.
- e) Annex E provides a TSF. This framework provides a formal description of signals similar to the signals defined in IEEE Std 716-1995. It also serves to illustrate how complex test signal models can be built up from BSCs.
- f) Annex F provides the IDL description for the TSF provided in Annex E.
- g) Annex G defines the requirements for a carrier language.
- h) Annex H provides the formal TPL description.
- i) Annex I provides the extensible markup language (XML) description mapping signal models into XML descriptions.
- j) Annex J provides XML description mapping the TSF provided in Annex E into XML descriptions.
- k) Annex K provides a description of how ATLAS nouns and noun modifiers are supported by STD.
- l) Annex L provides a bibliography of related documents.